



C800G7

Powering the Next Generation of AI and HPC Performance

Highlights

- Support Intel® Xeon® 6 processor with
 E-cores and P-cores, up to 550W
- Support DDR5 RDIMM, up to 7200 MT/s @ 1DPC
- Support 4 FHFL double slot GPU card
- Support up to 16 U.2 SSD or 16 SATA HDD
- Modular architecture to provide customers with the best performance platform
- Maximize serviceability with front IO and front node servicing









The Inventec C800G7 is purpose-built to deliver the compute power, scalability, and efficiency demanded by today's AI, HPC, and data-intensive workloads. It supports the latest Intel® Xeon® 6 processors E-cores and P-cores, giving customers the flexibility to choose the variants to best match their performance and efficiency requirements. With CPU power support up to 550 W, the C800G7 can fully unleash the capabilities of these processors, ensuring sustained performance even during the most demanding computational tasks.

Performance Architecture Built for Speed and Flexibility

Designed for future-ready computing, the C800G7 supports DDR5 RDIMM memory running at up to 7200 MT/s (1DPC) to maximize data throughput. It can host up to four FHFL double-slot GPUs, delivering massive parallel processing power for AI training, HPC simulations, and technical computing. Flexible storage options allow configurations of up to 16 U.2 NVMe SSDs or 16 SATA HDDs, catering to different requirements for speed, capacity, or a balanced mix. The system is equipped with an advanced air cooling solution for stable performance under heavy loads, with an optional liquid cooling configuration available for scenarios requiring enhanced thermal management in high-density or high-power deployments.



Tailored for Demanding Single-Node Performance

With its 2U1N single-node design, the C800G7 is ideal for vertically scaled, compute-intensive workloads that benefit from avoiding internode communication latency. This makes it particularly well-suited for HPC simulations requiring high memory bandwidth, Al training and inference that demand consolidated local resources, and high-performance databases where rapid in-node data access is critical. By combining the flexibility of Intel® Xeon® 6 architecture with powerful GPU acceleration, versatile storage, and multiple cooling options, the C800G7 provides a robust foundation for the next generation of Al and HPC innovation.

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Form Factor	2U1N Rackmount W x H x D: 447.6x87x 850 mm (17.63x 3.43x 33.46inch)
Processor	Intel® Xeon® 6900P series processor Intel® Xeon® 6900E-series processors Future Intel® Xeon® Clearwater Forest CPU
Memory	12 channels DDR5 per CPU 1DPC/12 DIMMs DDR5 RDIMM: up to 7200MT/s @1DPC
Storage/ PCle Card	Configuration: Config 1: 16x3.5"HDD+2xFHHL PCle Card (12xNVMe+2PCle Slot) (16x3.5"HDD+HBA+2xPCleSlot) Config 2: 12x3.5"HDD+HBA+5xPCleSlot (12xNVMe+2xPCle Slot) Config 3: 16x3.5"HDD+4x2.5"HDD (16xNVMe+4x3.5"HDD+HBA+OCP) (16x3.5"HDD+4xNVMe+HBA+OCP) Config 4: 8x3.5"HDD+4xDW GPU+DW PCle Card +HBA(6x3.5"HDD+2xNVMe+HBA+4xDW GPU +DW PCle Card) Config 5: 16x2.5"HDD+2xFHHL PCle Card Config 5(Front IO):18x2.5"HDD+1xFHHL PCle Card Internal: Support 2x22110/2280 M.2 for boot device
Expansion slots	Support 11x MCIOx8 Connector + 1x MCIOx4 Connector
Network Controller	support 1 x PCIe Gen5 x16 x OCP Support NCSI
Management Port	Support Aspeed AST2600 BMC NCSI connect to OCP 3.0, 10M/100M/1G Ethernet MAC controller
Power Supply	DC 12V From 1+1 CRPS
Fan	5+1x 6056 Fans @35'C ambient temperature with one fan rotor fail condition

About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

Inventec Corporation (TAO)

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